# MLX73290-M

# Melexis

# 300 to 960MHz Multi-Channel Transceiver With Flex RF Front-End

# 1. Features and Benefits

- Flex TX/RX RF front-end for antenna and frequency diversity
- Energy harvesting interface
- Transmitter with power detectors
- Receiver with digital RSSI
- Receiver self polling with MCU wake-up
- Multi-band frequency coverage from 300MHz up to 960MHz
- Modulation schemes supported: (G)FSK, (G)MSK, (G)OOK
- Transmitter power of -20 to 13dBm, 64 steps
- Receiver sensitivity of -120dBm (FSK, 433MHz, 15kHz CHBW)
- Supply voltage range of 2.1 to 3.6V
- PLL synthesizer with 60Hz resolution

- Channel filter bandwidth of 9 to 600kHz
- Data rate of 0.3 to 250kbps (GFSK)
- Frequency deviation up to 125kHz
- 32MHz crystal frequency
- Comprehensive supply monitoring & error handling capabilities
- SPI programmable in stand-by mode
- Multi-channel sensing and packet recognition
- 256byte FIFO (can be split 128/128 for RX/TX)
- 4 programmable GPIO ports
- 32L QFN5x5 package
- Compliant to EN 300 220, DASH7, FCC part 15, ARIB STD-T67, IEEE802.15.4 and other standards

# 2. Application Examples

- Automatic meter reading (AMR)
- Remote controls
- Home and building automation
- Alarm and security systems
- Garage door openers

- Medical applications
- Telemetry
- Industrial appliances
- Automotive keyless entry
- Tire pressure monitoring

# 3. Ordering Code

Product	Temperature	Package	Option	Packaging Form
MLX73290	R (-40°C to 105°C)	LQ (32L QFN5x5)	BBM-000	RE (reel 5000 pcs.)

# 4. Introduction

The MLX73290-M is a 300 to 930MHz multi-channel transceiver chip. The IC is designed for general purpose applications for example in the European bands at 433MHz and 868MHz or for similar applications in North America or Asia, e.g. at 315MHz or 915MHz. It is also well-suited for narrow-band applications which meet the ARIB standard STD-T67 in the frequency range 426MHz to 470MHz.

The output power, frequency channel, modulation type and frequency deviation are programmable via the serial programming interface (SPI). The synthesizer operates with a fractional-N PLL and VCO with integrated inductor. The small frequency resolution of the MLX73290-M and its PLL phase noise performance facilitate it for narrow-band operation. There are five selectable modulation schemes: on-off keying (OOK), binary frequency shift keying (FSK) and minimum shift keying (MSK) as well as their Gaussian filtered versions (GFSK and GMSK). The low-IF receiver part comprises fully digital demodulation and self-polling features together with channel scanning and packet recognition.



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# 5. Version History

Data sheet version	Date	Value
Rev 001	July 2012	First public release, preliminary version
Rev 002	Oct 2012	Corrections, packed handler added, preliminary version
Rev 003	Dec 2012	PA control information added
Rev 004	Mar 2013	Receiver self polling with MCU wake-up, register name OOK_MOD changed to RF_BIAS, performance plots added
Rev 005	Jun 2013	ACR, blocking parameters and more performance plots added
Rev 006	Sep 2013	More GPIO description added
Rev 007	Oct 2013	Flow chart for RF state machine added
Rev 008	May 2015	Temperature codes redefined and general update
Rev 009	Sep 2015	General update, modulation settings added
Rev 010	Dec 2016	Carrier frequency acceptance range added

# **6. Absolute Maximum Ratings**

Parameter	Symbol	Value	Units
Supply Voltage	$V_{DD}$	0 to 4	V
Operating Temp. Range	T <sub>A</sub>	-40 to 105	°C
Storage Temperature	T <sub>S</sub>	-55 to 125	°C
Range			
ESD Sensitivity (HBM)	$V_{ESD}$	±2	kV
ESD Sensitivity (CDM)	$V_{ESD}$	±0.5	kV

Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# 7. Pin Definitions and Pin-out

Pin №	Name	Туре	Function				
1	VPA	Supply	Supply of PA				
2	VSSA	Ground	Analog Ground				
3	PD1	RF analog	RF Power Detector 1				
4	RF1P	RF analog	RF port 1 - positive				
5	RF1N	RF analog	RF port 1 - negative				
6	NC		Not connected				
7	NC		Not connected				
8	VSSA	Ground	Analog Ground				
9	VHARV	Analog	Energy harvesting input				
10	VDDD3	Supply	Battery supply (dedicated to power switch)				
11	VMAIN	Supply	Power switch output for host MCU				
12	VDIG	Regulated supply	Digital voltage regulator output				



Pin №	Name	Туре	Function
13	VSSD	Ground	Digital Ground
14	GPIO3	Analog/Digital	General Purpose IO3
15	GPIO2	Analog/Digital	General Purpose IO2
16	CS	Digital	SPI Chip Select
17	GPIO1	Analog/Digital	General Purpose IO1
18	GPIO0	Analog/Digital	General Purpose IO0
19	SDO	Digital	SPI Slave Data Output
20	SDI	Digital	SPI Slave Data Input
21	SCK	Digital	SPI Clock
22	VSSA	Ground	Analog Ground
23	XTALN	Analog	Crystal negative input
24	XTALP	Analog	Crystal positive input
25	VDDA3	Supply	Analog supply
26	VANA	Regulated	Analog voltage regulator output
		supply	
27	VSSA	Ground	Analog Ground
28	RF2N	RF analog	RF port 2 - positive
29	RF2P	RF analog	RF port 2 - negative
30	PD2	RF analog	RF Power Detector 2
31	VSSA	Ground	Analog Ground
32	VDDA3	Supply	Analog Supply
EP	VSSA	Exposed pad	Analog Ground to be connected to GND on PCB

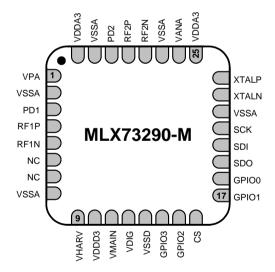


Figure 1: Pin-out of MLX73290-M





Figure 2: Picture of MLX73290-M devices

# 8. Electrical Specifications

# 8.1. Normal Operating Conditions

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Supply voltage	$V_{DD}$		2.1	3.0	3.6	V
Operating temperature (R)	T <sub>A</sub>	R version	-40	27	105	°C
Input low voltage (CMOS)	$V_{IL}$	Digital pins	-	-	0.3 * V <sub>DD</sub>	V
Input high voltage (CMOS)	V <sub>IH</sub>	Digital pins	0.7 * V <sub>DD</sub>	-	-	V

# 8.2. General Characteristics

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
		Timers				
Un-calibrated RC Oscillator	f <sub>RCclk</sub>		19	32	35	kHz
Calibrated RC Oscillator	$f_{RCclkCal}$		1	15.6	-	kHz
		General purpose	ADC			
Effective Number Of Bits	ENOB		-	10	-	bit
Sample Rate	SR		4	-	16	kS/s
Temperature sensor						
Sensitivity	temp <sub>sens</sub>		-	-1.6	-	mV/°C
Offset	temp <sub>off</sub>	25°C	-	750	-	mV

# 8.3. RF Characteristics

Operating Conditions:  $T_A = -40^{\circ}\text{C}$  to  $105^{\circ}\text{C}$ ,  $V_{DD} = 2.1\text{V}$  to 3.6V (unless otherwise specified)

Typical values at  $T_A = 25^{\circ}C$  and ,  $V_{DD} = 3.0V$ 

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units	
General							
Frequency Range	$f_{RF,band1}$		299	-	331		
	$f_{RF,band2}$		425	-	480	MHz	
	$f_{RF,band3}$	reserved for future use	ı	-	-	IVIITIZ	
	$f_{RF,band4}$		850	-	960		
Operating currents							



Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Sloop modo	1	deep sleep	-	200	-	nA
Sleep mode	I <sub>SLEEP</sub>	RCO on	-	400	-	IIA
	I <sub>RX,315MHz</sub>		-	14	-	
RF Receive mode	I <sub>RX,433MHz</sub>	100kbps, FSK, NRZ	-	15	-	mA
M Necelve mode	I <sub>RX,868MHz</sub>	1001000, 1311, 1112	-	16	-	
	I <sub>RX,915MHz</sub>		-	17	-	
	I <sub>ТХ,315МНz</sub>	100kbps, FSK, NRZ, OdBm	-	14	-	
	TIX,315MHZ	100kbps, FSK, NRZ, 10dBm	-	23	-	
		100kbps, FSK, NRZ, 0dBm	-	15	-	
RF Transmit mode	I <sub>TX,433MHz</sub>	100kbps, FSK, NRZ, 10dBm	-	25	-	т Л
Kr Hansilit Mode	I	100kbps, FSK, NRZ, 0dBm	-	24	-	mA
	I <sub>ТХ,868МНz</sub>	100kbps, FSK, NRZ, 10dBm	-	36	-	
	I <sub>TX,915MHz</sub>	100kbps, FSK, NRZ, 0dBm	-	25	-	
		100kbps, FSK, NRZ, 10dBm	-	37	-	
		Transmitter				
Max. CW output power at highest power step	P <sub>max,315MHz</sub> P <sub>max,433MHz</sub> P <sub>max,868MHz</sub> P <sub>max,915MHz</sub>	with 50Ω matching network	-20	13	-	dBm
Spurious emissions < 1GHz		Complies with EN 300	-	-	-54	dBm
Spurious emissions > 1GHz	$P_{spur}$	220 , FCC part 15and ARIB	-	-	-30	dBm
Optimum impedance of matching network	R <sub>OUT</sub>	single ended at output, Pout=13dBm		50		Ω
		Receiver				
FSK receiver sensitivity	P <sub>FSK,315MHz</sub>	315MHz	-	-120	-	dBm
2.4kbps NRZ FSK	P <sub>FSK,433MHz</sub>	433MHz	-	-120	-	dBm
Δf=±4kHz BW=15kHz, BER=10 <sup>-3</sup>	P <sub>FSK,868/915MHz</sub>	868/915MHz	-	-116	-	dBm
OOK receiver sensitivity	P <sub>OOK315MHz</sub>	315MHz	-	-115	-	dBm
2.4kbps NRZ BW=15kHz,	P <sub>OOK433MHz</sub>	433MHz	-	-115	-	dBm
BER=10 <sup>-3</sup>	P <sub>OOK868/915MHz</sub>	868/915MHz	-	-114	-	dBm
Image rejection	IMR	after IQ calibration w/o IQ calibration	40	50 25	-	dB
IF frequency	f <sub>IF</sub>	, , ,	-	fc/64	-	kHz
Channel filter bandwidth (digital)	CHBW	programmable	9	-	600	kHz



Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Input intercept point	IIP3	at max. gain		-28		dBm
Adjacent channel	A CD	OKUZ CUDW. (C)ECK		16		40
rejection	ACR	9kHz CHBW, (G)FSK	1	46	-	dB
	5114	2MHz offset (50kHz CHBW)	-	52	-	dB
Blocking	BLK	10MHz offset (50kHz CHBW)	-	71	-	dB
		Timings				
PA ramp up/down			_			
duration		programmable	0	-	192	μs
Channel switching time	t <sub>switch</sub>	max frequency step	-	-	300	μs
RX/TX turn-around time	$\Delta t_{RXTX}$		-	-	50	μs
Sleep to RX on time	t <sub>RX</sub>	programmable	200	-	-	μs
Sleep to TX on time	t <sub>TX</sub>	programmable	200	-	-	μs
		Modulator and data rate				
FSK deviation	Δf	Programmable in steps	-	-	±125	kHz
GFSK normalized BW	BT	fixed	-	0.5	-	
OOK modulation depth	M <sub>OOK</sub>	100% modulation	70	80	-	dB
	$DR_{FSK}$	NRZ coding FSK	0.15	-	250	kbps
Data rate	DR <sub>OOK</sub>	NRZ coding OOK	0.15	-	50	kbps
		Synthesizer				
Diversities	N <sub>PH 10kHz</sub>	@ 10kHz offset	-	-	-94	dBc/Hz
Phase noise	N <sub>PH_1MHz</sub>	@ 1MHz offset	-	-	-110	dBc/Hz
Frequency resolution	f <sub>RES</sub>		57	61	65	Hz
RX/TX switching time	$\Delta t_{RXTX}$		-	-	50	μs
RX or TX frequency					1.5	
change			1	-	15	μs
		Crystal oscillator				
Crystal oscillator frequency	$f_0$		30	32	34	MHz
Crystal oscillator start- up time	t <sub>ROstart</sub>		-	0.8	1	ms
	Rec	commended crystal specifica	ation			
Crystal frequency		, , , , , , , , , , , , , , , , , , , ,				
accuracy	$\Delta f_0$		-	-	±30	ppm
Load capacitance		Recommended for ext.				_
(differential)	$C_L$	crystal	8	12	15	pF
Static capacitance	Co	Recommended for ext. crystal	-	-	5	pF
Maximum Drive Level	MDL	Recommended for ext.	-	-	100	μW
Equivalent series resistance (ESR)	R <sub>1</sub>	Recommended for ext.	-	-	70	Ω



# 8.4. SPI Characteristics

Operating Conditions:  $T_A = -40^{\circ}$ C to  $105^{\circ}$ C,  $V_{DD} = 2.1$ V to 3.6V (unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
SPI Clock Frequency	$f_{SCLK}$		-	1	10	MHz
SCK high time	t <sub>SCKH</sub>	SCK ↑ to SCK ↓	40	-	-	ns
SCK low time	$t_{SCKL}$	SCK ↓ to SCK ↑	40	-	-	ns
SCK period	$t_{SCK}$	Between equal edges of	100	-	-	ns
		SCK				
Setup time	$t_{SU}$	CS and SDI stable to SCK ↑	20	-	-	ns
Hold time	$t_{HD}$	SCK ↑ to CS or SDI	20		-	ns
		changing				
SDO data delay	$t_{SDO}$	SCK ↓ to SDO stable	-	20	-	ns
Output enable delay	t <sub>OE</sub>	SCK ↓ to SDO output	-	20	-	ns
		enabled				
Output disable delay	t <sub>op</sub>	CS ↓ to SDO tri-state	-	50	-	ns

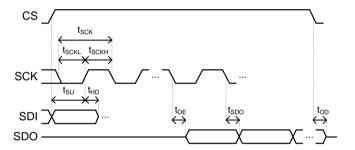


Figure 3: SPI timing specifications

# 9. Functional Description

# 9.1. Frequencies and Standards

The MLX73290-M complies with the following frequency bands and radio standards.

freq. band [MHz]	max. ERP [dBm]	channel BW [kHz]	max. data rate [kbps]	Comment
300-330	-20	0.25% of	20 (OOK, FSK)	SRDs - FCC 15.231
		center freq.		Japan ULP Band
426-469	10	12.5 - 25	5 (FSK)	Japan (ARIB), Korea
433-434	10	not defined	200 (OOK, FSK)	SRDs - EN 300 220, DASH7
446-447	10	25	1.2 (FSK)	Europe PMR, US FSR
863-870	14	25 - 600	250 (OOK, FSK)	SRDs - EN 300 220
902-928	-1	200 (typ.)	250 (OOK, FSK)	SRDs - FCC 15.249



# 9.2. Block Diagram

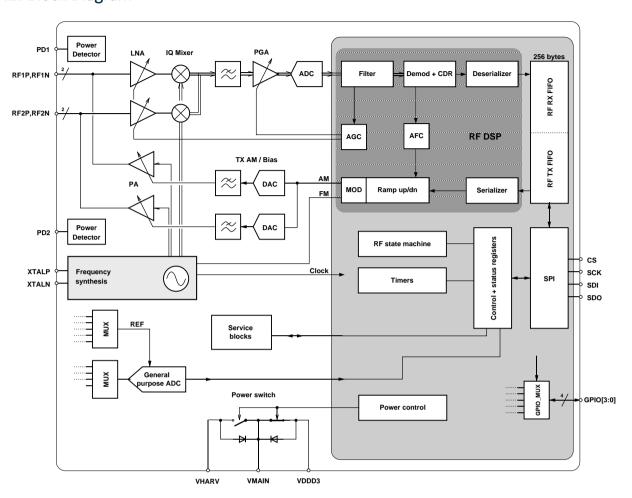


Figure 4: MLX73290-M block diagram (supply pins not shown)

# 9.3. Detailed Description

The MLX73290-M is fully programmable via its serial programming interface (SPI). The four SPI lines are configured as a standard 3-wire bus (CS, SCLK and SDI) plus an additional data output SDO providing feedback to an external microcontroller. This allows the changing of many parameters of the transceiver; for example to set up operating modes, channels, frequency resolutions, output power, modulation types, frequency deviation, polling modes and more.

The frequency synthesizer uses a fractional-N PLL that can be modulated with a  $\Sigma$ - $\Delta$  modulator. The VCO is fully integrated. Frequency deviations of the crystal oscillator (XOSC) can be simply compensated by adding offsets to the control words of the  $\Sigma$ - $\Delta$  modulator. Gaussian filtering of the input data signal is implemented for FSK and MSK modulation in order to provide a more narrow output spectrum.

The two TX/RX RF ports are combined differential I/O port for half-duplex operation; the LNAs and the PAs of each port are internally connected. The PA output power is programmable in 64 steps ranging from -20 dBm to +13 dBm. Output power switching of the PAs is always done with a programmable slew rate or Gaussian filtering in order to limit the transient output spectrum.



A low voltage detector disconnects the RF signal from the PAs if the supply voltage drops below a certain threshold value. This prevents the transmission of undesired frequencies at the battery's end of life.

In order to minimize the load of the host MCU, a packet handler takes care of formatting/pre-processing the data in both Receive & Transmit mode.

An on-chip power switch selects the supply voltage either from the battery (VDDA3) or from the energy-harvesting input (VHARV). It also provides the supply for the external host MCU (VMAIN).

Self-polling is realized by an integrated timer with very low power consumption. The polling mode wakes up the receiver or transmitter after a programmable time and scans one or more frequency channels for valid data. It can also be used to transmit the same data in a periodic way.

A transparent transmit or receive mode can also be chosen by selecting clock and data on GPIO pins.

## 9.4. RF Transceiver

The MLX73290-M is compliant with EN 300 220, FCC part 15 and ARIB STD-67 standards. It also supports DASH7 modes 1 and 2, as well as proprietary OOK, (G)MSK and (G)FSK-modulated communication protocols in ISM and SRD applications between 300 and 960MHz. Data rates between 0.15 and 250kbps, FSK deviations of up to 125kHz and RF output power levels between -20dBm and +13dBm can be used.

## 9.4.1. Flex TX/RX Front-End

The RF front-end consists of two differential TX/RX ports for half-duplex operation. Possible configurations are described below.

# Low-cost, single-antenna TX/RX configuration

- RF port 1 is connected to a single antenna through a matching network (MNW)
- LNA1 is active in RX mode only
- PA1 is active in TX mode only
- Power detector 1 can be used for sensing the power at the antenna
- PA2, LNA2 and power detector 2 are not used

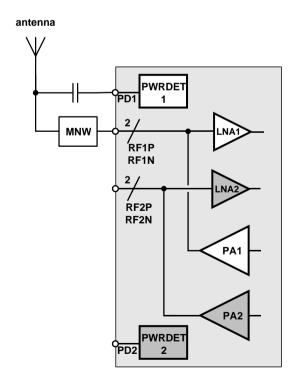


Figure 5



## High-end, single-antenna TX/RX configuration

- RF port 1 operates in RX mode only
- RF port 2 operates in TX mode only
- RF port 2 connects to an external PA for boosting the TX power (e.g. up to 20dBm)
- RF port 1 and external PA output are connected to one antenna through a MNW
- External PA can be turned on/off via a GPIO pin
- Power detector 1 can be used for sensing the power at the antenna

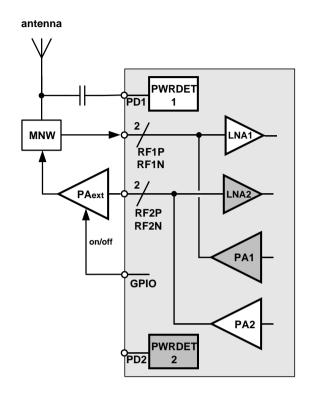


Figure 6

## Antenna space or frequency diversity configuration

- RF port 1 is connected to antenna 1
- RF port 2 is connected to antenna 2
- the two RF ports operate at the same frequency

#### → antenna space diversity

the two RF ports operate at different frequencies

## → frequency diversity

 Power detectors 1 and 2 can be used for sensing the power at the antennas

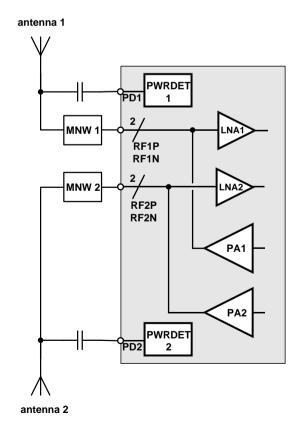


Figure 7



# 9.4.2. Frequency Synthesizer

At the analog heart of the RF transceiver is a frequency synthesizer based on a Sigma-Delta fractional-N PLL. From a typical 32MHz crystal reference clock, the PLL derives a quadrature LO-signal used for the mixers in the receive mode and to generate the carrier frequency in transmit mode. The PLL division ratio consists of a 6-bit integer part and a 19-bit fractional part, yielding to a resolution of 60Hz. The VCO of the PLL requires to be calibrated; for this purpose a calibration algorithm is implemented in the digital domain of the MLX73290-M device.

# 9.4.3. Transmit Mode (TX)

In RF transmit mode, the MLX73290-M outputs a CW signal on the two differential RF outputs RFP and RFN. The output power of the two PAs can be configured from -20dBm to 13dBm by the control bits RFTX\_PWR1 and RFTX\_PWR2 with the following tuning range:

- bits [7:6] for selecting the output stages 1 to 4,
- bits [5:3] for selecting the octave range (octave 000 = power OFF, 111 = power saturation),
- bits [2:0] for linear power tuning.

The frequency of the CW signal can be adjusted with the bits CENTER\_FREQ[24:0] according to the formula below.

$$f_{RF} = \frac{f_{XTAL} \cdot CENTER_{FREQ[24:0]}}{2^{19}}$$

The RF transmit band has to be selected accordingly with the bits BAND\_SEL[1:0].

A packet handler reads data stored into the RFTX\_FIFO to construct an RF packet including the programmable preamble, the synchronization word, a fixed or variable length of payload (up to 255 bytes), an optional address byte, and an optional CRC-16 checksum inserted at the end. The serializer block supports the specific data formats of IEEE 802.15.4 and DASH7 mode 2. The bit order (LSB or MSB first) and bit polarity are configurable. After optional data whitening and Manchester encoding, the data stream of the serialized RF packet enters the OOK or FSK modulator.

In case of OOK modulation, the PLL-based frequency synthesizer is programmed to the wanted carrier frequency and the power amplifier (PA) is switched ON and OFF.

In case of FSK modulation, the data stream is converted to a frequency deviation programmable between 0 and 125 kHz. The FSK signal directly modulates the PLL of the frequency synthesizer.

For both OOK and FSK modulation, the data stream can be selected with optional Gaussian pulse shaping (EN\_GAUSSIAN) to reduce the spectral bandwidth of the transmitted RF signal.

# 9.4.4. Receive Mode (RX)

The receiver chain features an IQ receiver topology. The RF signal is converted to the low IF band by an image reject mixer (the IF is at 500kHz). In order to address a wide dynamic range, the LNA as well as the programmable gain amplifier (PGA) conditions the IF signal. An automatic gain control loop ensures a stable signal level at the



input of the ADC which translates the signal to the digital domain. The base-band signal path features digital channel filtering, demodulation and extraction of clock and data. A de-serializer is used for extracting the payload from an incoming packet and it writes the payload to a FIFO that can be read out by the SPI.

A packet handler scans the demodulated signal for valid bit pattern followed by a programmable synchronization word of 16, 24 or 32 bits (SYNC\_WORD[31:0] and SYNC\_WORD\_LEN[1:0]) and a fixed or variable length of payload (RFRX\_FIFO of up to 255 bytes). An optional de-whitening operation as well as CRC-16 checksum verification could be enabled to reduce the load of the external host microcontroller.

#### 9.4.4.1. Automatic Receiver Polling

With the bits POLL\_RFRX and EN\_POLL, the MLX73290-M can be configured in automatic polling mode, using a programmable interval based on a 16-bit timer clocked with the internal calibrated RC oscillator (typ. At 15.6kHz), pre-scaled by a binary power of 2<sup>15</sup> giving a maximum interval of 38 hours.

At the end of the waiting periods, the timer restarts and sets the corresponding IRQ flag TMR\_FLAG, the MLX73290-M is set in receiver mode looking for a valid synchronization word (SYNC\_WORD[31:0]), during a certain time, as defined in the State Machine sec. below. The RX period might be preceded by periodic recalibration as configured by CALIB\_MODE. The RF state machine will eventually return to its stopped (idle) state after completion of the task (e.g. packet received) or when an error occurs (e.g. RX termination timer expires, PLL out of lock, FIFO overrun etc.). In the meantime, the polling timer continues to run, so the polling grid is in no way affected by how long it takes the RF transceiver to return to its idle state. This is important for RF protocols with beacons or timeslots at fixed intervals.

The following picture shows the basic functionality of the RF polling feature.

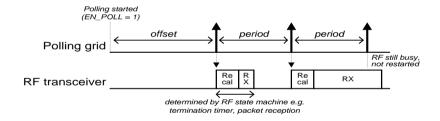


Figure 8: RF self-polling grid

The offset and polling period are configured with the registers POLL\_EXP[4:0], POLL\_OFFSET[15:0] and POLL\_PERIOD[15:0] according to the following formulas:

$$Offset = \frac{2^{(11+POLL_{EXF})} \cdot (1+POLL_{OFFSET})}{f_{XTAL}} [sec]$$

$$Period = \frac{2^{(11+POLL_{EXF})} \cdot (1+POLL_{PERIOD})}{f_{XTAL}} [sec]$$



#### 9.4.4.2. RSSI Information

RSSI information is available for the user in the register RSSI\_HDR[6:0] which contains the RSSI information measured just after a valid Header is detected.

## 9.4.4.3. Carrier Frequency Acceptance Range

With its carrier recovery feature the MLX73290-M is able to tolerate a carrier frequency range of up to  $\pm 2 \cdot DR$ , with DR being the raw data rate. The carrier frequency acceptance range (CFAR) does not depend on the AFC setting. The AFC just enables the carrier recovery to converge packet after packet to a given value. This potentially allows the preamble length to be reduced, if losing a few packets at the beginning is tolerated.

Fig. 9 illustrates the packet error rate (PER) vs CFAR. The example here is given for DR = 55.6kbps with a ±50kHz FSK modulation. As can be seen, that there is a tradeoff between the preamble length (which is the part of the packet during which the carrier recovery tries to converge) and the PER.

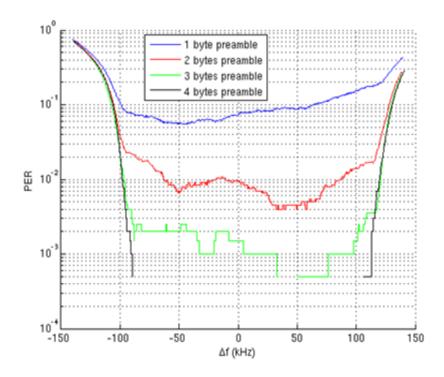


Figure 9: CFAR ( $\Delta f$ ) at different preamble lengths



# 9.4.5. State Machine

The RF state machine supports a wide range of autonomous operations requiring little or no MCU overhead.

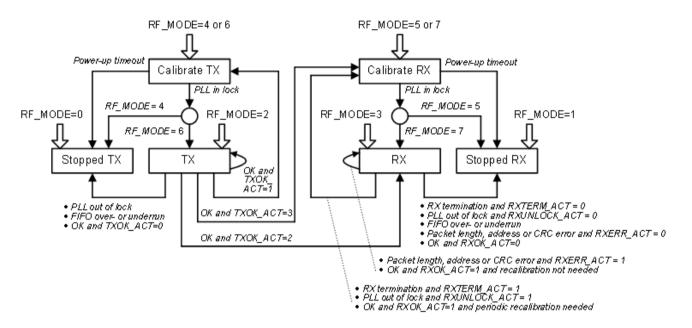


Figure 10: RF state machine flow chart

To request a state change, the host MCU will write to the flag RF\_MODE[2:0]:

- Calibrate TX/RX, then stop: to perform just a VCO calibration and nothing more
- Calibrate RX, then RX : to calibrate the VCO, then start reception
- RX waiting for header : to start reception, skipping the VCO calibration
- Calibrate TX, then TX: to calibrate the VCO, then start transmission
- TX transmitting payload : to start transmission, skipping the VCO calibration
- Stopped RX/TX: to abort any operation and return to the idle state

While writing to RF\_MODE, the host MCU may also write a 0 to the RFTXFIFO\_USE and RFRXFIFO\_USE flags in the same register to clear the RF TX and/or RF RX FIFOs.

In receive mode, the MLX73290-M first waits for a matching synchronization word defined in registers SYNC\_WORD[31:0], then move to the "RX receiving payload" state and start the reception of the payload. When the entire packet has been received, the RF\_RXFLAG flag will be set, and the state machine will take the action selected by RXOK\_ACT: it will stop, or resume RX after periodic recalibration as configured by CALIB\_MODE (please refer to section Automatic Polling Mode).

After successful reception, the MCU can read RSSI\_HDR[6:0] and AFC\_HDR[6:0] to obtain the RSSI and AFC values that have been measured during the reception of the packet (just after the SYNC\_WORD). It may also read the TMR\_HDR[15:0] to determine how much time has elapsed since the start of the received packet after the



SYNC\_WORD detection, which is particularly useful in slotted protocols, where the next transmission or reception should start at a certain distance relative to the beginning of the received packet.

If a CRC and/or address check is enabled, and the packet gets rejected on that basis, RXERR\_ACT will determine whether the state machine will stop and report a CRC or address error, or flush the RF RX FIFO and resume the reception.

Furthermore there is the option to set a threshold RX\_RSSI\_TH on the RSSI, below which reception is inhibited, and there is a termination timer programmable between 64µs and 32s (RXTERM\_MANT[3:0] and RXTERM\_EXP[3:0]). When the timer expires, termination may be postponed while RSSI is above the threshold, or while payload is being received, depending on the setting of the bit RXTERM\_COND. Then the state machine will take the action selected by RXTERM\_ACT: it will stop or recalibrate and resume reception.

When the PLL gets out of lock, depending on RXUNLOCK\_ACT the state machine will stop and report a PLL out-of-lock error or it will take the same actions as for termination. When there is an overrun/underrun on the RFRXFIFO, the state machine will stop and report a FIFO overrun/underrun error (RFRX\_FIFO\_USE) which can also be output on one GPIO.

**Important Note:** To enable the RF RX functionality, the register RF\_BIAS[7:0] in Bank 0 has to be set to 0x4C for the 315MHz band, to 0x63 for the 433MHz band and to 0x99 for the 868MHz and 915MHz bands.

In transmit mode, after transmission of the payload, the state machine will, depending on TXOK\_ACT, stop, resume TX after periodic recalibration as configured by CALIB\_MODE, or, after optional calibration, enter RX mode.

When DIRECT\_MOD > 2 direct modulation with a fixed logic 0 or 1 level, or from one of the GPIO digital input pins is selected. In this case the data-handler is bypassed and it is the responsibility of the microcontroller to terminate the transmission by changing RF\_MODE. This mode will allow for the transmission of un-modulated as well as modulated carriers for characterization, test and type approval. A clock at the programmable symbol rate can be output on one of the GPIO pins for transmission of a synchronous bit stream.

When the PLL gets out-of-lock during transmission, the state machine will always abort and report a PLL out of-lock error (PLL\_LOCKED). When there is an overrun/underrun on the RFTXFIFO, the state machine will stop and report a FIFO overrun/underrun error (RFTX\_FIFO\_USE).

By putting KEEP\_PLL\_ON to '1', the PLL can be kept running regardless the state of the RF transceiver, this is particularly useful for protocols where transmission or reception is triggered by an event and the normal startup delay of the PLL cannot be tolerated.

## 9.5. Modulation Settings

The below table provides an overview on the modulation settings. Continuous modulation can also be applied through the GPIOs. In this case the selected GPIO pin must be set as a digital input.



Modulation	mod_source	FSK/OOK	Manchester	Data- whitening	Comment
Continuous wave	Fixed logic 1	оок	disable	disable	
Continuous modulation FSK Manchester	Fixed logic 1 or Fixed logic 0	FSK	enable	disable	
Continuous modulation FSK data whitening	Fixed logic 1 or Fixed logic 0	FSK	disable	enable	
Continuous modulation FSK GPIO	GPIO 0 GPIO 1 GPIO 2 GPIO 3	FSK	enable or disable	enable or disable	refer to sec 5.12 for GPIO input selection
Continuous modulation OOK Manchester	Fixed logic 1 or Fixed logic 0	оок	enable	disable	
Continuous modulation OOK data whitening	Fixed logic 1 or Fixed logic 0	оок	disable	enable	
Continuous modulation OOK GPIO	GPIO 0 GPIO 1 GPIO 2 GPIO 3	ООК	enable or disable	enable or disable	refer to sec 5.12 for GPIO input selection

# 9.6. Packet Handler

The MLX73290-M embeds a packet handler mechanism for managing the encoding/decoding of the transmit/receive bytes contain in the RF FIFO. Different frame formats are supported and can be fully configured by the user. Figure 9 shows the different frame formats supported in transmit and receive modes.

The packet handler is enabled with the bit **en\_packet** in transmit mode and with the bit **en\_deserializer** in receive mode. Both bits are available in registers 0x18 and 0x27, respectively.



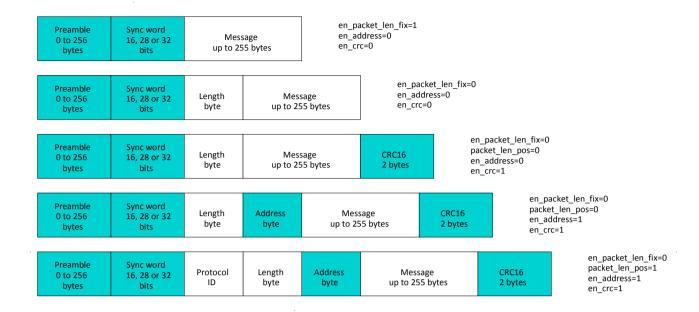


Figure 11: Packet handler - frame formats

#### 9.6.1. Preamble

A preamble can be automatically added to the packet structure even if it is completely handled by the host MCU. This feature can be turned on by simply setting the bit **en\_preamble** signal to 1. The length of the preamble is given by the signal **pattern\_world\_len[1:0]** (number of times that the preamble byte is repeated) and the preamble itself is given by the **preamble[7:0]** in bank 0 (by default to 0x55).

#### 9.6.2. Sync Word

The synchronization word is introduced automatically if the preamble is present. The length of the sync word is given by the **sync\_word\_len**. The synchronization word is always sent LSB first.

## 9.6.3. Packet Length

If the packet handler is enabled, it has to know the length of the packet to be sent/received. This one can be fixed or variable depending on the user settings. If the fixed solution is chosen, the **en\_packet\_len\_fix** has to be set to 1. In this case the length of the packet is given by the byte **packet\_len[7:0]**.

In the case of a variable packet length (en\_packet\_len\_fix set to 0), the length is normally specified as one of the first bytes of the packet. The byte packet\_len\_pos[1:0] specify the position of this byte (e.g. if set to 0, means that the first byte sent/received is defining the packet length).

The packet handler always considers the length of the packet from the first byte after the packet length byte until the last byte before the CRC. The bit **packet\_len\_corr** specify the correction to apply to the packet length. This gives the possibility for the user to provide/receive frame format with a length byte including itself and/or is included in the CRC computation.

The following picture shows the **packet\_len\_corr** principle.



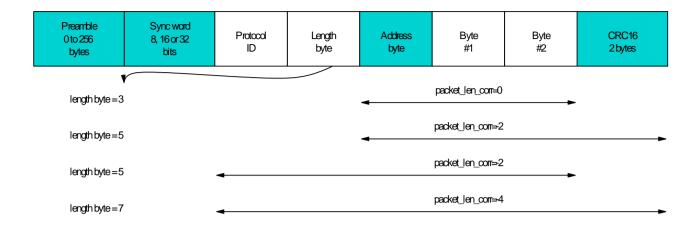


Figure 12: Packet handler - packet correction principle

## 9.6.4. Address

An address can be inserted automatically after the packet length if the bit **en\_address** is set to 1. The address is given by the byte **address**[7:0].

#### 9.6.5. CRC16

A checksum CRC16 can be automatically computed and added/compared to the packet sent/received, by setting the bit **en\_crc** to 1. In case of reception, the status bits **rfrx\_flag** and **rf\_info[2:0]** will be automatically updated in case of CRC error.

#### 9.6.6. Multi Frame

If the **en\_multi\_frame** bit is set to 1, the multi-frame mode is enabled. A frame is composed by the data and the corresponding CRC. In this mode, a preamble and a single synchronization word are followed by multiple frames. As long as the **en\_multi\_frame** bit is set to 1, the packet handler continues to send/receive frames.

#### 5.5.7 Data Whitening

The packet handler also includes a data whitening process during the transmission or the reception of RF packets. In this case, all the data to be sent/received are encoded/decoded using a PN9 polynomial of  $X^9+X^5+1$ . The data-whitening process is illustrated in the picture below. The data whitening process is enabled with the bit **en\_white**.



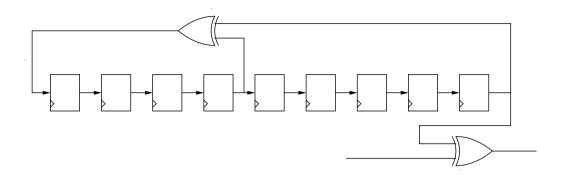


Figure 13: Packet handler – frame data whitening PN9 structure

# 9.7. Power Management and Energy Harvesting

The power management unit of the MLX73290-M is performing the following operations:

- It measures the battery voltage (VDDA3) at power-on reset (POR) and decides whether the voltage is sufficient to power up the MLX73290-M and to supply the host MCU through pin VMAIN (if  $\geq 2.1V$ ).
- If the measured voltage at VDDA3 is below the threshold level (of approx. 2V) then pin VHARV is used to supply the MLX73290-M and the host MCU.
- After power-on, the internal power switch is locked to avoid switching back and forth between modes.
- When the IC is running, the power switch can still be controlled via the SPI to select the supply source between VHARV or VDDA3 (Register 0x0C of Bank0).
- The status of the power management state machine can be queried via SPI (Register 0x03 of Bank0).
- The voltage at VHARV can be read via the general purpose ADC.

Different monitoring blocks are used to report the status of the internal and external voltages, and to keep the digital control blocks in reset mode as long as the supply voltage has not reached a sufficient value:

**Power-on reset (POR):** This block is to maintain the digital circuitry in reset mode as long as the supply voltage is below a certain level at start-up. When the supply voltage is sufficient, the reset mode is deactivated after a certain delay, which has to be sufficient to ensure correct internal state. While this is not a monitoring function per se, the state of the reset signal gives an indication as to when the supply voltage has reached the necessary level for the digital functionalities to work properly (meaning mainly that the configuration registers are able to retain their state).

**Brownout detector (BOD):** Detects when the supply voltage drops below a certain threshold, even momentarily. The threshold should correspond to a voltage below which the digital functionalities cannot be guaranteed. The threshold crossing is detected without great precision but with a very low-power consumption (less than 100nA). This monitoring block is mainly intended to be used for brownout detection when the overall power consumption is of key importance so that the band-gap voltage reference cannot be used.

**Low-battery detector (LBD):** Uses the band-gap reference voltage to detect whether or not the external battery voltage is above or equal its specified minimum level of 2.1V.



# 9.8. Programmable Timer / Clock Generator

A programmable timer / clock generator may periodically wake up the host MCU or it can provide a clock signal, derived from the RC oscillator, the calibrated RC clock or the crystal clock. A prescaler first divides the selected clock source by a programmable binary power between 1 and 231, and then by an 8-bit linear division ratio between 1 and 256.

The timer period is configured with the bits TMR\_MANT[7:0] and TMR\_EXP[4:0]. The following formula can be used to calculate the timer period, relative to the clock source selected by the bits TMR\_SOURCE[1:0]:

$$TMR_{PERIOD} = \frac{(TM_{MANT} + 1) \cdot 2^{TMR_{EXP}}}{f_{SOURCE}}$$
 [sec]

The timer can be selected in Timer or Clock mode with the bit TMR\_MODE. In Timer mode, the timer stops when the flag gets set, and the MCU must clear the flag to restart the timer. In Clock mode, the timer is continuously running thus providing a reference clock for the host MCU.

The timer is, by default configured to output the RC oscillator clock signal on GPIO2 without any division (i.e. ratio 1:1) so that it may act as a clock signal for the MCU. There is also the possibility to configure the timer output to another GPIO.

For more information about the programmable timer, please refer to section 10.4.

# 9.9. System Timer

The MLX73290-M embeds a 23-bit free-running counter that can serve as a time reference. When enabled, it increments at 7.8 kHz derived from the calibrated RC clock. Counter overflows (every  $^{\sim}18$  minutes) will set a flag, which may wake-up the microcontroller. The firmware can then clear the flag and increment a counter in the microcontroller to extend the counter range to any length. To determine the elapsed time between two events, take a snapshot of this free-running system time at both moments and subtract these two values to find the elapsed time with 128  $\mu$ s resolution.

For more information about the system timer, please refer to section **10.4**.

# 9.10. General Purpose ADC

The external host MCU can use a built-in 10-bit general purpose ADC to measure several internal signals selected with the bits ADC\_CH\_SEL[3:0] (e.g. supply voltages, output of the RF power detectors, 3D LF field strength, temperature sensor, analog level of one of the GPIO pins). The ADC can be configured for continuous sampling or a single measurement (ADC\_CONTINU bit set).

The conversion clock can be set to  $1/16^{th}$ ,  $1/32^{nd}$  or  $1/64^{th}$  of the crystal clock (ADC\_CLK\_SEL[1:0]), corresponding to a period of conversion of respectively  $t_{AD} = 0.5$ , 1 or 2  $\mu$ s with a 32MHz crystal. A full conversion cycle takes 128 clocks leading to a conversion time of 64, 128 or 256  $\mu$ s, resulting in 16, 8 or 4 kS/s throughput.

The conversion is started with the bit ADC\_START\_EOC and the result stored into the register ADC\_CAL[9:0]. Since the conversion results are 10 bit wide, the microcontroller will need to read them as 2 bytes through the SPI interface. This is an asynchronous process, so when the ADC operates in continuous sampling mode, the



completion of a new conversion may coincide with the retrieval of the 2 bytes of the results of the previous conversion. Without special provisions the microcontroller may receive the first byte of the old conversion and the second byte of the new conversion, which could give a false reading. To prevent such inconsistencies, the generic ADC therefore takes a snapshot of the conversion results when the first byte is read, and returns the second part of the snapshot when the second byte is read in the same (burst mode) read access.

The generic ADC maintains a flag, ADC\_NEWDATA, to indicate whether new results are available, primarily intended for continuous sampling mode. The completion of a conversion will set the flag, and reading the first byte of the results will clear the flag. The microcontroller may poll this flag to check if a new sample is available, and if so, it may continue reading the two byte result, which will clear the flag.

#### 9.11. SPI Communication

The serial programming interface (SPI) is composed of three inputs and one output as shown in the following table.

SPI pin	1/0	Description
CS	input	SPI Chip Select active high
SDO	output	SPI Slave data output
SDI	input	SPI Slave data input
SCK	input	SPI Clock

The SDO pin is set high impedance by the MLX73290-M when not transmitting SPI information; this allows a configuration using only one pin to successively send/receive information from/to the MLX73290-M. The two configurations using classical 4-pin and optimized 3-pin are illustrated below:

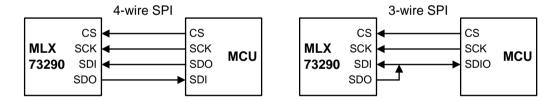


Figure 14: SPI connections

In Read mode, the serial data changes on the falling edges of the serial clock and is latched, during write mode, on the rising clock edges. Data are transmitted MSB first.

Opposite to most conventional SPI devices, the CS chip select input of the MLX73290-M is active **high**. When the CS is set low, the MLX73290-M is deselected as SPI-slave; SCK and SDI can take any level, and SDO is tri-state. When CS goes high, the MLX73290-M becomes selected, and expects from the host MCU, a 7-bit register address preceded by one bit of direction (0 = write, 1 = read).

A so-called Burst mode is implemented in the MLX73290-M which automatically increment the address of the current register to be read/write. This operation is illustrated in the picture below:



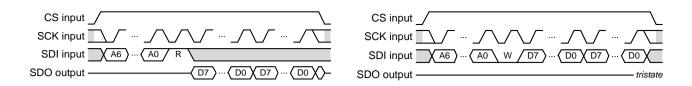


Figure 15: (burst) read/write SPI

The picture above is valid to address standard registers. To address the specific BankO, the following procedure should be followed.

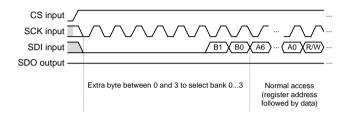


Figure 16: Specific access to BankO register

# 9.12. GPIO Pins

Four general purpose I/O (GPIO) pins are available in the MLX73290-M (GPIO0 to GPIO3). Several digital signals can be output, e.g. to be further used by the host MCU. Each GPIO pin has an 8-bit GPIOx\_CH\_SEL[7:0] setting that configures the I/O type of the corresponding pin (analog/digital, in/output) and the signal routing to/ from the pin.

GPIOx_ CH_SEL [7:0]	Signal	I/O type
x0000000	Disabled	Disabled
x0000001	GPIOx_Y with pull-down	Digital input
x0000010	GPIOx_Y with pull-up	Digital input
x0000011	GPIOx_Y	Digital input
x000010x : x0000110	Reserved	Disabled
x0000111	Internal analog line, pulled down	Analog I/O
x0001000 : x0001011	Reserved	Analog I/O
x0001100	PD1	Analog I/O
x0001101	PD2	Analog I/O
x0001110	TEMPSENS	Analog I/O
0001xxxx	See table 10, signal level	Push-pull digital



001xxxxx	inverted when	output
01xxxxxx	$GPIOx\_CH\_SEL[0] = 1$	
1001xxxx	See table 10, signal level	Open collector digital
101xxxxx	inverted when	output
11xxxxxx	$GPIOx\_CH\_SEL[0] = 1$	

The default values of GPIOs after power-on reset (POR) are:

GPIO0 : READYGPIO1 : READY\_NOTGPIO2 : TMR\_FLAGGPIO3 : BATTOK

The digital signals are active high (unless otherwise specified). For GPIOx as digital output, the following truth table applies:

GPIOx_CH_SEL[6:1]	Signal Name	Description
001000	Fixed logic 0	
001001	READY	MLX73290-M is ready after start-up sequence (POR)
001010	ВАТТОК	Battery level measured above the minimum level 2.1V.
001011	RCO	Output of un-calibrated internal RC oscillator
010100	LOWBAT	Output of low battery detector on VDDA3
010101	XTAL_RDY	Crystal clock is present and stable
011000	ADC_NEWDATA	New result from general purpose ADC available
011001	SYS_TIME_OVF	Internal system timer overflow
011010	TMR_FLAG	Programmable timer flag
011011	POLL_FLAG	RF Polling timer flag
011100	PLL_CYCLE_SLIP	A PLL cycle-slip has been registered since the last read from this register
011101	PLL_IN_LOCK	PLL successfully locked
011110	RFRX_CLK	RF Clock output after data-handler
011111	RFRX_DATA	RF Data output after data-handler
100000	RFRX_WAIT_HDR	RF state-machine waiting for valid Header
100001	RFRX_PAYLOAD	RF state-machine receiving the payload
100010	RFRX_WAIT_HDR_PAYLOAD	RF state-machine waiting for valid Header or receiving Payload
100011	RFTX_PAYLOAD	RF state-machine transmitting payload
100100	RF_STOPPED	RF state-machine stopped (RX or TX)
100101	RF_STOPPED_ERR	RF state-machine stopped with an error (RX or TX)



GPIOx_CH_SEL[6:1]	Signal Name	Description
100110	RFTX_FIFO_OVRUDR	RF TX FIFO overrun/underrun error
100111	RFRX_FIFO_OVRUDR	RF RX FIFO overrun/underrun error
101000	RFRX_FIFO_1BYTE	RF RX FIFO contains at least 1byte
101001	RFRX_FIFO_64BYTES	RF RX FIFO contains at least 64bytes
101010	RFTX_FIFO_1BYTE	RF TX FIFO contains at least 1byte
101011	RFTX_FIFO_64BYTES	RF TX FIFO contains at least 64bytes
101100	RFTX_SYM_CLK	RF TX Manchester symbol clock
101101	RFRX_RSSI_ABOVE_THR	RX RSSI measured above threshold
101110	RFRX_PKT	RF Data-handler packet received

# 10. Register Settings

The MLX73290-M is addressed through a set of 126 unbanked registers for standard use (addresses from 0x02 to 0x7F). One additional bank of 128 registers (Bank 0) is also available for specific information (addresses from 0x00 to 0x7F).

# 10.1. RF Transceiver (0x02 to 0x33)

Addr	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	
		RF Transceiver							
02	TMR_HDR[7:0]								
03				TMR_H	DR[15:8]				
04				Rese	rved				
05				R	SSI_HDR[6:0	)]			
06				Rese	rved				
07				Rese	rved				
08	Reserved								
09	Reserved								
0A	DR_OFFSET[7:0]								
OB	LNA_12DB	LNA_AT	TEN[1:0]		PO	PGA_GAIN[4:0]			
0C		FILT	ER_GAIN_E[	[2:0]		FILTER_GAIN_M[2:0]		[2:0]	
0D	EN_CORR ECT_ISI	EN_FINE _RECOV	EN_ROUGH _RECOV	EN_FAST_ PRE_CR	DR_OFFS_ ADJUST	AFC_M(	DDE[1:0]	EN_CORRE CT_CFREQ	
0E									
OF									
10	Reserved								
11	Reserved								
12	RFTX_PWR1[7:0]								
13				RFTX_PV	VR2[7:0]				
14				SYNC_W	ORD[7:0]				



15	SYNC_WORD [15:8]								
16				SYNC_WO	RD [23:16]				
17				SYNC_WO	RD 31:24]				
18	EN_D7M1	D7M1_ TAG_NINT	EN_MULTI _FRAME	EN_ DESERIAL	PATTERN_ AL WORD_LEN[1:0]		PATTERN_ MAX_ERR[1:0]		
19	FIFO_SIZE			N_POS[1:0]					
1A				PACKET_	LEN[7:0]				
1B				ADDRE	SS[7:0]				
1C	CEN	TER_FREQ[2	2:0]						
1D				CENTER_F	REQ[10:3]				
1E				CENTER_FF	REQ[18:11]				
1F					CENTER_FF	REQ[24:19]			
20			PWRDET2 _EN	PWRDET1 _EN	RF_FE_	EN[1:0]	BAND_S	SEL[1:0]	
21	DR_LIM	IIT[1:0]					DR_E[2:0]		
22					DR_M	1[5:0]			
23	MULT_EXP[3:0]				MULT_MANTISSA[3:0]				
24					Т	X_RAMP[2:0	)]		
25	PREAMBLE_LEN[7:0]								
26	IQ_CORR _EN	IQ_CORR _CAL	RF_RSSI_	DEC[1:0]	1:0] RF_CHANBW[3:0]				
27	LSB_FIRST	BIT_ INVERT	EN_MAN CHESTER	EN_DATA WHITE	EN_ PREAMBLE	EN_ PACKET	EN_CRC	EN_ ADDRESS	
28	FSK_NOOK	EN_ GAUSSIAN	EN_INTERP	POSNEG_ MIX	POSNEG_IF	DIR	RECT_MOD[2	2:0]	
29						RX_RSSI	_TH[3:0]		
2A		RXTERM_	EXP[3:0]			RXTERM_MANT[3:0]			
2B	RXTERM_C	COND[1:0]				CA	CALIB_MODE[2:0]		
2C				PWRUP_ MODE	PWRUP_TIME[3:0]				
2D	RXTERM _ACT		RXUNLOCK _ACT	RXERR _ACT	RXOK _ACT		TXOK_A	ACT[1:0]	
2E	RF_MODE[2:0]			POV	VER_MODE[	2:0]	RFTXFIFO _USE	RFRXFIFO _USE	
2Fr	RF_ RXFLAG RF_MODE_SHORT[1:0]			1	RE INFO[2:0] RFTXFIFO RFRXF			RFRXFIFO _USE	
2Fw	RF_MODE[2:0]						RFTXFIFO _USE	RFRXFIFO _USE	
30				RFTXFIFO <sub>.</sub>	_CNT[7:0]		<u> </u>	<u> </u>	
31	RFRXFIFO_CNT[7:0]								
32r				RFRXFI	FO[7:0]				



32w	RFTXFIFO[7:0]
33	RANDOM[7:0]

Table - Unbanked register map: RF Transceiver

Bit(s)	Signal	R/W	Init	Description
70	TMR_HDR[7:0]	R	-	Snapshot of the lower byte of the system time, taken after the detection of a valid header

Table 1: Unbanked register 0x02

Bit(s)	Signal	R/W	Init	Description
70	TMR_HDR[15:8]	R	1	Snapshot of the middle byte of the system time, taken after the detection of a valid header.  To ensure consistency between the bytes, use one SPI access cycle to read both bytes of TMR_HDR

Table 2: Unbanked register 0x03

Bit(s)	Signal	R/W	Init	Description
7	Reserved	R	0	Not used, reads as 0
60	RSSI_HDR[6:0]	R	-	RSSI value frozen after header detection, 1.5 dB increments

Table 3: Unbanked register 0x05

Bit(s)	Signal	R/W	Init	Description
70	AFC[7:0]	RW	0	Lower byte of AFC value

Table - Unbanked register 0x06

Bit(s)	Signal	R/W	Init	Description
70	AFC[15:8]	RW	0	Upper byte of AFC value; to ensure consistency between the bytes, use one SPI access cycle to read both bytes of AFC.

Table - Unbanked register 0x07

Bit(s)	Signal	R/W	Init	Description
70	DR_OFFSET[7:0]	RW	0	Data rate offset in clock recovery

Table - Unbanked register 0x0A

Bit(s)	Signal	R/W	Init	Description
7	LNA_12DB	RW	0	<u>Dis</u> able -12 dB attenuation in stage 1 of the LNAs
65	LNA_ATTEN[1:0]	RW	0	2-bit attenuation control in stage 2 of the LNAs : 0 = -18 dB 1 = -12 dB



				2 = -6 dB 3 = 0 dB
40	PGA_GAIN[4:0]	RW	0	5 LSBs of 6-bit PGA gain setting, in 2 dB increments

Table - Unbanked register 0x0B

Bit(s)	Signal	R/W	Init	Description
7	Reserved	R	0	
64	FILTER_GAIN_E[2:0]	RW	0	Gain of the matched filter (exponent)
3	Reserved	R	0	
20	FILTER_GAIN_M[2:0]	RW	0	Gain of the matched filter (mantissa)

Table - Unbanked register 0x0C

Bit(s)	Signal	R/W	Init	Description
7	EN_CORRECT_ISI	RW	0	Enable the ISI (Inter-Symbol-Interference) correction
6	EN_FINE_RECOV	RW	0	Enables fine carrier recovery
5	EN_ROUGH_RECOV	RW	0	Enables rough carrier recovery
4	EN_FAST_PRE_CR	RW	0	Enables fast carrier recovery during the preamble
3	DR_OFFS_ADJUST	RW	0	Adjust data rate :  0 = no adjustment  1 = update DR_OFFSET at the end of the packet
21	AFC_MODE[1:0]	RW	0	AFC mode selection:  0 = no AFC  1 = AFC on the fei_ok signal  2 = AFC at the beginning of the payload  3 = AFC at the end of the packet
0	EN_CORRECT_ CFREQ	RW	0	Enable frequency correction

Table - Unbanked register 0x0D

Bit(s)	Signal	R/W	Init	Description
70	RFTX_PWR1[7:0]	RW	0	Output power RF1, see sec. 5.4.3 for details

Table - Unbanked register 0x12

Bit(s)	Signal	R/W	Init	Description
70	RFTX_PWR2[7:0]	RW	0	Output power RF2, see sec. 5.4.3 for details

Table - Unbanked register 0x13

Bit(s)	Signal	R/W	Init	Description
70	SYNC_WORD[7:0]	RW	0	First byte of synchronization word

Table - Unbanked register 0x14



Bit(s)	Signal	R/W	Init	Description
70	SYNC_WORD[ [15:8]	RW	0	Second byte of synchronization word

Table - Unbanked register 0x15

Bit(s)	Signal	R/W	Init	Description
70	SYNC_WORD[ [23:16]	RW	0	Third byte of synchronization word

Table - Unbanked register 0x16

Bit(s)	Signal	R/W	Init	Description
70	SYNC_WORD[ [31:24]	RW	0	Fourth byte of synchronization word

Table - Unbanked register 0x17

Bit(s)	Signal	R/W	Init	Description
7	EN_D7M1	RW	0	Enable DASH7 mode 1
6	D7M1_TAG_NINT	RW	0	DASH7 mode 1 : 0 = interrogator 1 = tag
5	EN_MULTI_FRAME	RW	0	Enable the reception and transmission of packets consisting of multiple frames
4	EN_DESERIAL	RW	0	Enable data-handler in RF RX
32	SYNC_WORD_ LEN[1:0]	RW	0	Length of the synchronization word:  0 = 16 bits  1 = 24 bits  2 = 32 bits  3 = no synchronization pattern  (only disables the pattern for RX, in TX  the full 32-bit pattern will be  transmitted)
10	SYNC_WORD_MAX_ER R[1:0]	RW	0	Maximum number of errors tolerated in received synchronization word

Table - Unbanked register 0x18

Bit(s)	Signal	R/W	Init	Description
7	FIFO_SIZE	RW	0	RF FIFO organization : 0 = single FIFO of 256 bytes 1 = two FIFOs of 128 bytes each
6	EN_PACKET_LEN_FIX	RW	0	Packet length : 0 = variable 1 = fixed
54	PACKET_LEN_POS [1:0]	RW	0	Position of the packet length byte, starting from the synchronization word (only applicable when the packet length is not fixed)
30	PACKET_LEN_CORR [3:0]	RW	0	Signed word that specifies how the packet length should be corrected

Table - Unbanked register 0x19



Bit(s)	Signal	R/W	Init	Description
70	PACKET_LEN[7:0]	RW	0	Packet length in fixed packet length mode, maximum packet length for receive with variable packet length

Table - Unbanked register 0x1A

Bit(s)	Signal	R/W	Init	Description
70	ADDRESS[7:0]	RW	0	Address to be transmitted or checked when address byte is enabled

Table - Unbanked register 0x1B

Bit(s)	Signal	R/W	Init	Description
75	CENTER_FREQ[2:0]	RW	0	Lower 3 bits of the fractional division ratio of the PLL for the center frequency
40	Reserved	R	0	Not used, reads as 0

Table - Unbanked register 0x1C

Bit(s)	Signal	R/W	Init	Description
70	CENTER_FREQ[10:3]	RW	0	Middle 8 bits of the fractional division ratio of the PLL for the center frequency

Table - Unbanked register 0x1D

Bit(s)	Signal	R/W	Init	Description
70	CENTER_FREQ[18:11]	RW	0	Upper 8 bits of the fractional division ratio of the PLL for the center frequency

Table - Unbanked register 0x1E

Bit(s)	Signal	R/W	Init	Description
76	Reserved	R	0	Not used, reads as 0
50	CENTER_FREQ[24:19]	RW	0	Upper 6 bits of the center frequency, corresponding to the integer division ratio of the PLL

Table - Unbanked register 0x1F

Bit(s)	Signal	R/W	Init	Description
76	Reserved	R	0	
5	PWRDET2_EN	RW	0	Enable power detector 2
4	PWRDET1_EN	RW	0	Enable power detector 1
32	RF_FE_EN[1:0]	RW	0	RF front-end mask : Bit 0 = Enable RF front-end 1 Bit 1 = Enable RF front-end 2
10	BAND_SEL[1:0]	RW	0	RF frequency band selection:  0 = 299 - 331 MHz frequency range  1 = 425 - 471 MHz frequency range  2 = 607 - 615 MHz frequency range



Table - Unbanked register 0x20

Bit(s)	Signal	R/W	Init	Description
76	DR_LIMIT[1:0]	RW	0	Limits of the data rate recovery: 0 = no data rate recovery $1 = \pm 3.1\%$ of the data rate $2 = \pm 6.3\%$ of the data rate $3 = \pm 12.5\%$ of the data rate
40	Reserved	R	0	
20	DR_E[2:0]	RW	0	Exponent to set the data rate

Table - Unbanked register 0x21

Bit(s)	Signal	R/W	Init	Description
76	Reserved	R	0	
50	DR_M[5:0]	RW	0	Mantissa to set the data rate

Table - Unbanked register 0x22

Bit(s)	Signal	R/W	Init	Description
74	MULT_EXP[3:0]	RW	0	Scaling to be applied to the pulse shaping coefficients by shifting them in the modulator, equivalent to 2 <sup>MULT_EXP</sup>
30	MULT_MANTISSA[3:0]	RW	0	Mantissa of the coefficient that multiplies the signal, equal to (16 + MULT_MANTISSA) / 16

Table - Unbanked register 0x23

Bit(s)	Signal	R/W	Init	Description
73	Reserved	R	0	Not used, reads as 0
20	TX_RAMP[2:0]	RW	0	TX ramp up/down duration: 0 = no ramp up/down 1 = 32 μs 2 = 16 μs 3 = 8 μs 4 = 192 μs 5 = 96 μs 6 = 48 μs 7 = 24 μs

Table - Unbanked register 0x24

Bit(s)	Signal	R/W	Init	Description
70	PREAMBLE_LEN[7:0]	RW	0	Length of the preamble to be transmitted

Table - Unbanked register 0x25



Bit(s)	Signal	R/W	Init	Description
7	IQ_CORR_EN	RW	0	Enable I/Q imbalance correction
6	IQ_CORR_CAL	RW	0	I/Q imbalance calibration in progress; set this bit to start I/Q imbalance calibration, automatically cleared by hardware when calibration is finished. Clear this bit to abort calibration. IQ_CORR_EN does not need to be set for the calibration.
54	RF_RSSI_DEC[1:0]	RW	0	Decay rate of RF RSSI: -1.5 dB at  0 = 1x symbol rate  1 = 2x symbol rate  2 = 4x symbol rate  3 = 8x symbol rate
30	RF_CHANBW[3:0]	RW	0	RF channel bandwidth:  0 = 600 kHz  1 = 300 kHz  2 = 200 kHz  3 = 150 kHz  4 = 120 kHz  5 = 100 kHz  6 = 75 kHz  7 = 60 kHz  8 = 50 kHz  9 = 38 kHz  10 = 30 kHz  11 = 25 kHz  12 = 19 kHz  13 = 15 kHz  14 = 13 kHz  15 = 9 kHz

Table - Unbanked register 0x26

Bit(s)	Signal	R/W	Init	Description
7	LSB_FIRST	RW	0	Select the bit order : 0 = MSB first 1 = LSB first
6	BIT_INVERT	RW	0	Invert the polarity of the data bits
5	EN_MANCHESTER	RW	0	Enable Manchester coding of the data bits
4	EN_DATAWHITE	RW	0	Enable data whitening
3	EN_PREAMBLE	RW	0	Enable transmission of a preamble
2	EN_PACKET	RW	0	Enable transmission and reception of packets
1	EN_CRC	RW	0	Add CRC to transmitted packets, check CRC of received packets
0	EN_ADDRESS	RW	0	Add address byte to transmitted packets, check address byte in received packets for match

Table - Unbanked register 0x27



Bit(s)	Signal	R/W	Init	Description
7	FSK_NOOK	RW	0	Select the modulation type : 0 = OOK 1 = FSK
6	EN_GAUSSIAN	RW	0	Enable Gaussian pulse shaping / matched filtering
5	EN_INTERP	RW	0	Enable interpolator on TX modulator output
4	POSNEG_MIX	RW	0	In RX, expect a positive or negative IF frequency in the down mixer
3	POSNEG_IF	RW	0	In RX, add or subtract the IF frequency to/from the center frequency (hi/lo-side injection)
20	DIRECT_MOD[2:0]	RW	0	Direct modulation source:  0, 1 = none, no direct modulation 2 = Fixed logic 0 3 = Fixed logic 1 4 = GPIO0 input 5 = GPIO1 input 6 = GPIO2 input 7 = GPIO3 input

Table - Unbanked register 0x28

Bit(s)	Signal	R/W	Init	Description
74	Reserved	R	0	Not used, reads as 0
30	RX_RSSI_TH[3:0]	RW	0	RSSI threshold value for carrier sense signal

Table - Unbanked register 0x29

Bit(s)	Signal	R/W	Init	Description
74	RXTERM_EXP[3:0]	RW	0	Exponent/Mantissa of RX termination timeout
				interval: $\frac{2048 \cdot (1 + RXTERM_{MANT})}{f_{xtalclk}}$
30	RXTERM_MANT[3:0]	RW	0	$115 = \frac{2048 \cdot \left( (RXTERM_{MANT} + 17) \cdot 2^{\left( RXTERM_{EXP} - 1 \right)} \right)}{f_{xtalclk}}$

Table - Unbanked register 0x2A

В	Bit(s)	Signal	R/W	Init	Description
7	76	RXTERM_COND[1:0]	RW	0	After timeout has expired, postpone termination:  0 = always (i.e. never terminate)



				<ul> <li>1 = never (i.e. terminate unconditionally)</li> <li>2 = as long as RSSI is above threshold,</li> <li>or payload is being received (after detection of a valid sync word)</li> <li>3 = as long as a payload is being received</li> </ul>
73	Reserved	R	0	
20	CALIB_MODE[2:0]	RW	0	Periodic (re)calibration mode:  0 = always recalibrate  1 = 1:4  2 = 1:8  3 = 1:16  4 = 1:32  5 = 1:64  6 = 1:128  7 = never recalibrate

Table - Unbanked register 0x2B

Bit(s)	Signal	R/W	Init	Description
75	Reserved	R	0	Not used, reads as 0
4	PWRUP_MODE	RW	0	Power-up sequence timing:  0 = Variable power-up time; the requested RF operation starts as soon as the power-up sequencing is completed  1 = Fixed power-up time; the requested RF operation starts after the timeout set by PWRUP_TIME[3:0], provided that the power-up sequence is completed
30	PWRUP_TIME[3:0]	RW	10	Timeout for power-up sequencing:  0 = 0.2 ms  1 = 0.25 ms  2 = 0.4 ms  3 = 0.5 ms  4 = 0.75 ms  5 = 1 ms  6 = 1.5 ms  7 = 2 ms  8 = 3 ms  9 = 4 ms  10 = 6 ms  11 = 8 ms  12 = 12 ms  13 = 16 ms  14 = 24 ms  15 = 32 ms  When the timeout expires before the power-up sequence is completed, the pending RF mode  (RX or TX) is aborted with an error

Table - Unbanked register 0x2C



Bit(s)	Signal	R/W	Init	Description
7	RXTERM_ACT	RW	0	Action to take for RX termination timeout 0 = go to error state 1 = flush RF RX FIFO, recalibrate RX, then RX
6	Reserved	R	0	Not used, reads as 0
5	RXUNLOCK_ACT	RW	0	Action to take when PLL gets out-of-lock in RX  0 = go to error state  1 = flush RF RX FIFO, recalibrate RX, then RX
4	RXERR_ACT	RW	0	Action to take when packet is received with incorrect length, address or CRC  0 = go to error state 1 = flush RF RX FIFO and restart RX
3	RXOK_ACT	RW	0	Action to take when packet received 0 = stop 1 = periodically (re)calibrate RX, then RX
2	Reserved	R	0	Not used, reads as 0
10	TXOK_ACT[1:0]	RW	0	Action to take upon TX completion  0 = stop  1 = periodically (re)calibrate TX, then TX  2 = RX  3 = calibrate RX, then RX

Table - Unbanked register 0x2D

Bit(s)	Signal	R/W	Init	Description
75	RF_MODE[2:0]	RW	0	Present RF mode:  0 = stopped TX  1 = stopped RX  2 = TX  3 = RX  4 = calibrate TX, then stop  5 = calibrate RX, then TX  7 = calibrate RX, then RX
42	POWER_MODE[2:0]	RW	3	Automatic power sequencer override:  0 = no override, VDIG, crystal oscillator and PLL  OFF unless requested by internal functions,  VDIG and crystal oscillator not kept ON when  RF RX or TX FIFO not empty  1 = Force VDIG and crystal oscillator ON,  POWER_MODE changes to 3 upon next write to  RF TX FIFO  2 = keep VDIG ON when RF RX or TX FIFO not  empty  3 = keep VDIG and crystal oscillator ON when  RF RX or TX FIFO not empty  4 = Force VDIG ON,  5 = Force VDIG ON,  keep crystal oscillator ON when RF RX or TX



				FIFO not empty 6 = Force VDIG and crystal oscillator ON 7 = Force VDIG, crystal oscillator and PLL ON
1	RFTXFIFO_USE	RW	0	RF TX FIFO status:  0 = empty, overrun or underrun  1 = not empty (in use)  Write 0 to flush RF TX FIFO, 1 to preserve FIFO  contents
0	RFRXFIFO_USE	RW	0	RF RX FIFO status:  0 = empty, overrun or underrun  1 = not empty (in use)  Write 0 to flush RF RX FIFO, 1 to preserve FIFO  contents

Table - Unbanked register 0x2E

Bit(s)	Signal	R/W	Init	Description
7	RF_RXFLAG	R	0	Packet received, with correct length, address and CRC (if checking enabled); cleared when RF RX FIFO is flushed or a byte is read from the RF RX FIFO
65	RF_MODE_SHORT [1:0]	R	0	Present RF mode (read-only):  0 = stopped TX  1 = stopped RX  2 = TX  3 = RX
42	RF_INFO[2:0]	R	0	Additional info on present RF mode, when RF_MODE = 0 or 1 (stopped RX / TX): 0 = OK  1 = Power-up sequence timed out 2 = PLL out of lock 3 = FIFO error (over- or underrun) 4 = RX termination timer expired 5 = Invalid packet length received 6 = Incorrect address received 7 = Incorrect CRC received When RF_MODE = 27 (calibrate, RX or TX): 0 = Powering up (LDOs, XTAL, PLL etc.) 1 = Calibrating VCO 2 = Waiting for PLL lock 3 = Reserved 4 = RX waiting for header 5 = RX receiving payload 6 = TX waiting for FIFO data 7 = TX transmitting payload
1	RFTXFIFO_USE	R	0	RF TX FIFO status: 0 = empty, overrun or underrun 1 = not empty (in use)
0	RFRXFIFO_USE	R	0	RF RX FIFO status:



		0 = empty, overrun or underrun
		1 = not empty (in use)

Table - Unbanked register 0x2F (read)

Bit(s)	Signal	R/W	Init	Description
75	RF_MODE[2:0]	W	0	Present RF mode:  0 = stopped TX  1 = stopped RX  2 = TX  3 = RX  4 = calibrate TX, then stop  5 = calibrate RX, then TX  7 = calibrate RX, then RX
42	Reserved	R	-	
1	RFTXFIFO_USE	W	0	Write 0 to flush RF TX FIFO, 1 to preserve FIFO contents
0	RFRXFIFO_USE	W	0	Write 0 to flush RF RX FIFO, 1 to preserve FIFO contents

## Table - Unbanked register 0x2F (write)

Bit(s)	Signal	R/W	Init	Description
70	RFTXFIFO_CNT[7:0]	R	0	Number of bytes in the RF TX FIFO When the FIFO contains 256 bytes, RFTXFIFO_CNT will be 0 but RFTXFIFO_USE will be active. When RFTXFIFO_USE is 0, RFTXFIFO_CNT is normally 0 (FIFO empty) but can also indicate an underrun (count = 254) or overrun (count = 255)

## Table - Unbanked register 0x30

Bit(s)	Signal	R/W	Init	Description
70	RFRXFIFO_CNT[7:0]	R	0	Number of bytes in the RF RX FIFO
				When the FIFO contains 256 bytes,
				RFRXFIFO_CNT will be 0 but RFRXFIFO_USE will
				be active. When RFRXFIFO_USE is 0,
				RFRXFIFO_CNT is normally 0 (FIFO empty) but
				can also indicate an underrun (count = 254) or
				overrun (count = 255)

## Table - Unbanked register 0x31

Bit(s)	Signal	R/W	Init	Description
70	RFRXFIFO[7:0]	R	-	Accesses the data in the RF RX FIFO
				The register address is not auto-incremented

Table - Unbanked register 0x32 (read)

Bit(s) Signal R/W Init Description
------------------------------------



70	RFTXFIFO[7:0]	W	-	Accesses the RF TX FIFO
				The register address is not auto-incremented

Table - Unbanked register 0x32 (write)

Bit(s)	Signal	R/W	Init	Description
70	RANDOM[7:0]	R	0	Random data, harvested noise of Sigma-Delta
				ADCs
				The register address is not auto-incremented

Table - Unbanked register 0x33

# 10.2. Status Byte & GPIOs (0x34 to 0x3B)

Addr	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
	Status							
34								
35	ВАТТОК	PLL_ LOCKED	CYCLE_ SLIP	RSSI_ GOOD	FEI_OK			
	GPIO multiplexing							
36					GPIO3	GPIO2	GPIO1	GPIO0
37	GPIO3_[	ORV[1:0]	GPIO2_I	DRV[1:0]	GPIO1_DRV[1:0]			
38				GPI	O0_CH_SEL[	6:0]		
39		GPIO1_CH_SEL[6:0]						
3A		GPIO2_CH_SEL[6:0]						
3B				GPI	O3_CH_SEL[	6:0]		

Table - Unbanked register map : Status & GPIOs

Bit(s)	Signal	R/W	Init	Description
7	BATTOK	R	-	Started in : 0 = Battery backup mode 1 = Normal mode
6	PLL_LOCKED	R	-	PLL is currently in-lock
5	CYCLE_SLIP	RC	-	A PLL cycle-slip has been registered since the last read from this register (cleared by reading this register)
4	RSSI_GOOD	R	-	RSSI level above threshold (carrier sense)
3	FEI_OK	R	-	Frequency error indicator stable
20	Reserved	R	0	

Table - Unbanked register 0x35

Bit(s)	Signal	R/W	Init	Description
74	Reserved	R	0	Not used, reads as 0
3	GPIO3	R	-	Current level of GPIO3
2	GPIO2	R	-	Current level of GPIO2
1	GPIO1	R	-	Current level of GPIO1



0	GPIO0	R	-	Current level of GPIO0

Table - Unbanked register 0x36

Bit(s)	Signal	R/W	Init	Description
76	GPIO3_DRV[1:0]	RW	0	Sets the driving strength of GPIO3 when used as digital output:  0 = 3 mA  1 = 6 mA  2 = 9 mA  3 = 12 mA
54	GPIO2_DRV[1:0]	RW	0	Sets the driving strength of GPIO2 when used as digital output
32	GPIO1_DRV[1:0]	RW	0	Sets the driving strength of GPIO1 when used as digital output
10	GPIO0_DRV[1:0]	RW	0	Sets the driving strength of GPIOO when used as digital output

Table - Unbanked register 0x37

Bit(s)	Signal	R/W	Init	Description
7	Reserved	R	0	
60	GPIO0_CH_SEL[6:0]	RW	0x12	See section <b>5.12</b>

Table - Unbanked register 0x38

Bit(s)	Signal	R/W	Init	Description
7	Reserved	R	0	
60	GPIO1_CH_SEL[6:0]	RW	0x13	See section <b>5.12</b>

Table - Unbanked register 0x39

Bit(s)	Signal	R/W	Init	Description
7	Reserved	R	0	
60	GPIO2_CH_SEL[6:0]	RW	0x34	See section <b>5.12</b>

Table - Unbanked register 0x3A

Bit(s)	Signal	R/W	Init	Description
7	Reserved	R	0	
60	GPIO3_CH_SEL[6:0]	RW	0x14	See section <b>5.12</b>

Table - Unbanked register 0x3B

# 10.3. General Purpose ADC (0x3C to 0x3F)

Addr	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
				GPADC				
3C	ADC_REF_SEL[2:0]				ADC_CH_SEL[3:0]			
3D	ADC_ NEWDATA				ADC_ CONTINU	ADC_CLK	_SEL[1:0]	ADC_START _EOC
3E		ADC_CAL[7:0]						



3F						1	ADC_CAL[9:8]
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Table - Unbanked register map: GPADC

Bit(s)	Signal	R/W	Init	Description
75	ADC_REF_SEL[2:0]	RW	0	Reference select for the generic ADC:  0 = bandgap voltage 1.2V  1 = VDDA3  2 = VDDA3 / 2  3 = VANA (1.7V nom)  4 = AIOO  5 = AIO1  6 = AIO2  7 = AIO3
4	Reserved	R	0	Not used, reads as 0
30	ADC_CH_SEL[3:0]	RW	0	Channel select for the generic ADC:  0 = 0.3 x VDDA3  1 = 0.3 x VHARV  2 = 0.6 x VDIG  3 = 0.6 x VANA  4 = 0.6 x VVCO  5 = 0.6 x VPA  6 = PD1  7 = PD2  8 = AIOO  9 = AIO1  10 = AIO2  11 = AIO3  12 = TEMPSENS  13 = 3D LF RSSI  14 = Reserved  15 = Reserved

Table - Unbanked register 0x3C

Bit(s)	Signal	R/W	Init	Description
7	ADC_NEWDATA	RW H/W set clear		New data sample available, can be cleared, not set. Set by hardware upon completion of an ADC measurement, automatically cleared by hardware when lower byte of conversion results is read.
64	Reserved	R	0	
3	ADC_CONTINU	RW 0		Generic ADC measurement mode :  0 = single measurement  1 = continuous measurement  Write protected when ADC_START_EOC = 1
21	ADC_CLK_SEL[1:0]	RW	0	Clock select for the general purpose ADC:  0 = RC oscillator (500 μs/conversion typ.)  1 = XTAL / 64 (256 μs/conversion)  2 = XTAL / 32 (128 μs/conversion)



				3 = XTAL / 16 (64 μs/conversion)
0	ADC_START_EOC	RW H/W clear	0	Enable general purpose ADC.  Set this bit to start ADC measurements, clear this bit to stop / abort ADC measurements.  Automatically cleared by hardware upon completion of an ADC measurement when ADC_CONTINU = 0 (single measurement mode), can be polled by host to wait for completion

Table - Unbanked register 0x3D

Bit(s)	Signal	R/W	Init	Description
70	ADC_CAL[7:0]	R	-	Lower byte of 10-bit conversion result of the generic ADC

Table 4: Unbanked register 0x3E

Bit(s)	Signal	R/W	Init	Description
72	Reserved	R	0	
10	ADC_CAL[9:8]	R	-	Upper bits of 10-bit conversion result of the generic ADC; to ensure consistency between the bytes, use one SPI access cycle to read both bytes of ADC_CAL

Table - Unbanked register 0x3F

# 10.4. Timers (0x40 to 0x4F)

Addr	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
Timers								
40				TMR_M	ANT[7:0]			
41	TMR_SOL	JRCE[1:0]	TMR_MODE		-	TMR_EXP[4:0	]	
42	TMR_FLAG							
43								
44				SYS_TII	ME[7:0]			
45				SYS_TIN	1E[15:8]			
46	SYS_TIME _OVF			S	'S_TIME[22:1	6]		
47	SYS_TIME _EN							
48				POLL_OF	FSET[7:0]			
49				POLL_OFF	SET[15:8]			
4A	POLL_PERIOD[7:0]							
4B	POLL_PERIOD[15:8]							
4C	EN_POLL POLL_FLAG POLL_RFRX POLL_EXP[3:0]							
4D								
4E				RC_CA	L[7:0]			
4F							RC_CAL[10:8]	



## Table - Unbanked register map: Timers

Bit(s)	Signal	R/W	Init	Description
70	TMR_MANT[7:0]	RW	0	8-bit period of programmable timer / clock generator; changes are glitch-free in clock generator mode Period = (TMR_MANT+1)·2 <sup>TMR_EXP</sup> clocks

Table - Unbanked register 0x40 (programmable timer)

Bit(s)	Signal	R/W	Init	Description
76	TMR_SOURCE[1:0]	RW	2	Clock source selector for programmable timer / clock generator: 0 = OFF, timer stopped and reset 1 = 32 MHz (typ.) crystal clock 2 = 32 kHz (typ.) RC oscillator 3 = 15.6 kHz (typ.) calibrated RC clock Changes are glitch-free in clock generator mode
5	TMR_MODE	RW	0	Mode of programmable timer / clock generator : 0 = Clock generator 1 = Timer
40	TMR_EXP[4:0]	RW	0	5-bit prescaler ratio of programmable timer / clock generator; changes are glitch-free in clock generator mode

Table - Unbanked register 0x41 (programmable timer)

Bit(s)	Signal	R/W	Init	Description
7	TMR_FLAG	RW	1	Output of programmable timer / clock generator IRQ flag in timer mode, that will stop the timer and needs to be cleared by the microcontroller
60	Reserved	R	0	Not used, reads as 0

Table - Unbanked register 0x42 (programmable timer)

Bit	t(s)	Signal	R/W	Init	Description
7.	0	SYS_TIME[7:0]	RC	0	Lower byte of 23-bit free-running system time Any write to this register will reset the entire system time including the overflow flag

Table - Unbanked register 0x44 (system timer)

Bit(s)	Signal	R/W	Init	Description
70	SYS_TIME[15:8]	RC	0	Middle byte of 23-bit free-running system time To ensure consistency between the bytes, use one SPI access cycle to read the lower, middle and upper byte of the system time

Table - Unbanked register 0x45 (system timer)



Bit(s)	Signal	R/W	Init	Description
7	SYS_TIME_OVF	RC	0	Overflow of the free-running system time, can be cleared by setting this bit to 0 through SPI
60	SYS_TIME[22:16]	RC	0	Upper byte of 23-bit free-running system time To ensure consistency between the bytes, use one SPI access cycle to read the lower, middle and upper byte of the system time

Table - Unbanked register 0x46 (system timer)

Bit(s)	Signal	R/W	Init	Description
7	SYS_TIME_EN	RW	0	Enable free-running system time Disabling the system time will pause the system time, but not clear it
60	Reserved	R	0	

Table - Unbanked register 0x47 (system timer)

Bit(s)	Signal	R/W	Init	Description
70	POLL_OFFSET[7:0]	RW	0	Lower byte of 16-bit offset of RF polling timer

Table - Unbanked register 0x48 (RF polling timer)

Bit(s)	Signal	R/W	Init	Description
70	POLL_OFFSET[15:8]	RW	0	Upper byte of 16-bit offset of RF polling timer $\frac{2^{(11+POLL_{EXP})} \cdot (1+POLL_{OFFSET})}{f_{xtalclk}}$ Sec

Table - Unbanked register 0x49 (RF polling timer)

Bit(s)	Signal	R/W	Init	Description
70	POLL_PERIOD[7:0]	RW	0	Lower byte of 16-bit period of RF polling timer

Table - Unbanked register 0x4A (RF polling timer)

Bit(s)	Signal	R/W	Init	Description
70	POLL_PERIOD[15:8]	RW	0	Upper byte of 16-bit period of RF polling timer  Period =
				$2^{(11+POLL_{EXP})} \cdot (1+POLL_{PERIOD})$
				$f_{xtalclk}$ sec

Table - Unbanked register 0x4B (RF polling timer)

Bit(s)	Signal	R/W	Init	Description	
7	EN_POLL	RW	0	Enable RF polling timer	
6	POLL_FLAG	RW	0	IRQ flag of RF polling timer, set when timer expires	
5	POLL_RFRX	RW	0	Enable RF RX polling	
4	Reserved	R	0		
30	POLL_EXP[3:0]	RW	0	4-bit prescaler ratio of RF polling timer	



## Table - Unbanked register 0x4C (RF polling timer)

Bit(s)	Signal	R/W	Init	Description
70	RC_CAL[7:0]	RW	0xE8	Lower byte of calibration value for RC oscillator = $f_{xtalclk} / f_{RCclk}$

Table - Unbanked register 0x4E (RCO calibration)

Bit(s)	Signal	R/W	Init	Description
73	Reserved	R	0	
20	RC_CAL[10:8]	RW	3	Upper bits of calibration value for RC oscillator. To ensure consistency between the bytes, use one SPI access cycle to read both bytes of RC_CAL. Write protected when calibrated RC clock is in use by one or more functions

Table - Unbanked register 0x4F (RCO calibration)

# 10.5. Chip ID and Soft Reset (register 0x7F)

Addr	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	
	Chip ID and soft reset								
7Fr				CHI	P_ID				
7Fw				SOFT	RESET				

Table - Unbanked register 0x7F

Bit(s)	Signal	R/W	Init	Description
70	CHIP_ID	R	0x11	Chip identification number

Table - Unbanked register 0x7F read

Bit(s)	Signal	R/W	Init	Description
70	SOFTRESET	W	-	Write 0x56 to trigger a soft reset of the chip.

Table - Unbanked register 0x7F write

## 10.6. Bank 0

Addr	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0				
	Test and spare signals											
0006												
07				PN9_ REVERSE	CRC_ RST_MODE	PN9_ MODE	PGA_ GAIN[5]	ADC_TEST				
08-3B												
3C				RF_E	BIAS[7:0]							
3D48												
49				PREAM	MBLE[7:0]							
4A53												

Table - Bank0 register map



Bit(s)	Signal	R/W	Init	Description
75	Reserved	R	0	Not used, reads as 0
4	PN9_REVERSE	RW	1	Generate PN9 sequence : 0 = LSB first 1 = MSB first
3	CRC_RST_MODE	RW	0	Initialize CRC to : 0 = 0x0000 1 = 0xFFFF
2	PN9_MODE	RW	1	Perform PN9 sequence with reversed byte.
10	Reserved	R	0	

Table 5 - BankO register 0x07

Bit(s)	Signal	R/W	Init	Description
70	RF_BIAS[7:0]	RW	0	Enable the RF RX functionality, has to be set to the following values depending on the frequency band selected:
				315MHz = 0x4C 433MHz = 0x63 868MHz and 915MHz = 0x99

Table - BankO register 0x3C

Bit(s)	Signal	R/W	Init	Description
70	PREAMBLE[7:0]	RW	0x55	Preamble pattern to be repeated according to PREAMBLE LEN[7:0] in unbanked register 0x25

Table - BankO register 0x49

# 11. Application Information

## 11.1. Typical Application Schematic

A possible application circuit of the MLX73290-M is shown in the below Figure. The circuit features two RF frontends with power detectors in place. Antenna space or frequency diversity can be performed via antenna 1 and antenna 2.

An energy harvester (like a solar cell) could be used for supplying the transceiver IC at pin VHARV. The MCU controls the RF transceiver via its SPI bus and it connects to the GPIO bus.



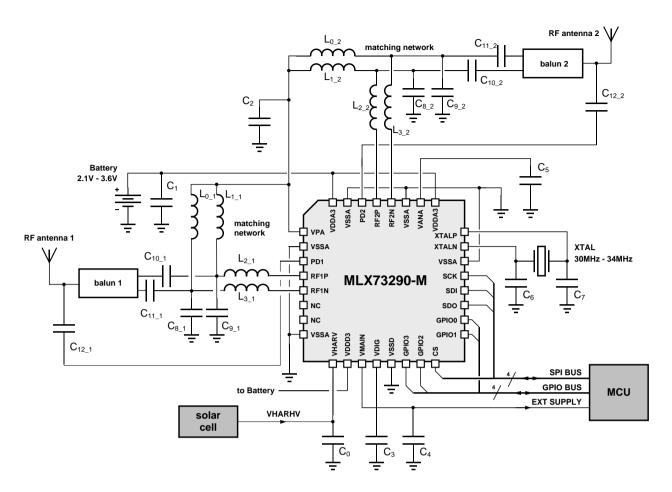


Figure 17: Typical application schematic

## 11.1.1. TX/RX Combining Network

The RF ports of the MLX73290-M have been designed in order to achieve optimum performance in both TX and RX mode as well as for different RF power levels and at various frequency bands. For this purpose two inductors are used per single-ended RF port. Pin VPA connects to the four inductors of the TX/RX combining network. In TX mode, this pin is internally switched to positive supply, and so it supplies the output transistor of the cascoded power amplifier (PA). In RX mode, pin VPA is internally connected to ground, and the transistor is now part of the LNA that behaves as a common-gate amplifier. As a result the RF port impedance in RX mode matches the impedance in TX mode, yielding optimum performance in both modes. An alternative TX/RX combining network with less inductors can be used (and will be presented later).

#### 11.1.2. Balun

A balanced-to-unbalanced transformer (balun) is used to convert the differential input/output of the MLX73290-M to a single-ended signal from/to the RF antenna. Off-the-shelf baluns are available on the market, depending on the wanted frequency range, the actual implementation will vary. Some SAW filters can also fulfil a balun functionality, which may be an interesting solution if it is necessary to filter out harmonics to comply with regulatory requirements. The easiest solution is to realize a lumped balun with discrete external components and integrated it within the RF matching network. A simple balun topology is illustrated below.



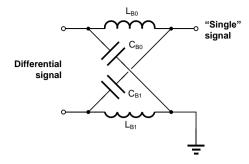


Figure 18: Balun made with discrete components

## 11.1.3. External Power Switch Usage

In the special case where the microcontroller does not have a low power standby mode (as would be for example the case with some dedicated secure code), the overall power consumption can be reduced by using the integrated polling mechanism and using an external power switch, e.g. a power MOSFET, as illustrated in Figure 19.

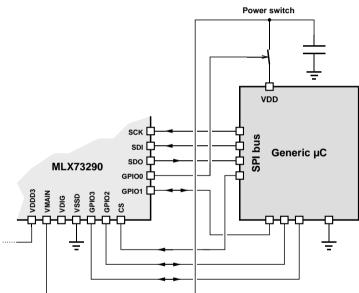


Figure 19: MCU supplied through an external power switch

In that specific case, one of the GPIO signals can be used to control an external power switch which is useful to cut down the residual power consumption of the microcontroller. Note that the chip select wire of the SPI interface has been defined *active high* specifically for this application. This avoids having the MLX73290-M "selected" when the microcontroller power is down.



## 12. Performance Plots

## 12.1. Spectrum Plots

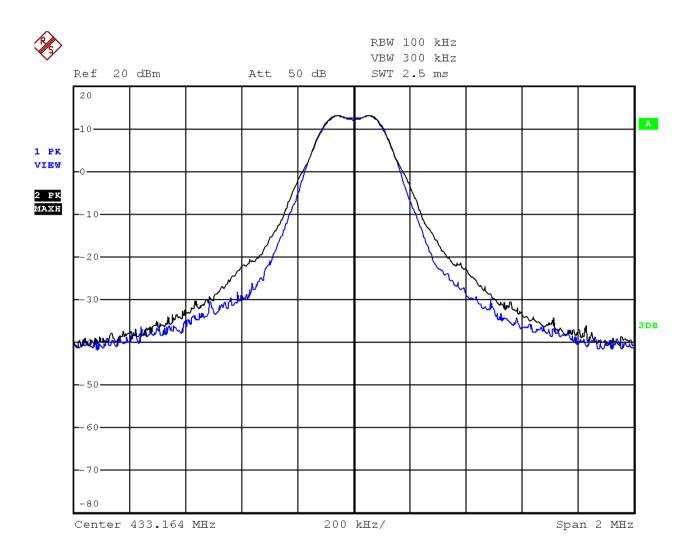


Figure 20: FSK (black) and GFSK (blue) spectrum at 250kbps, ±50kHz deviation



## 12.2. Eye Diagram

Ch1 2FSK Meas Time

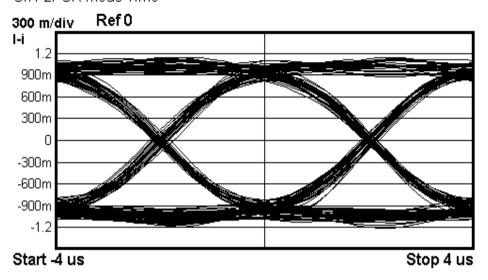


Figure 21: 250kbps GMSK transmit signal eye diagram at 868MHz

## 12.3. Phase Noise

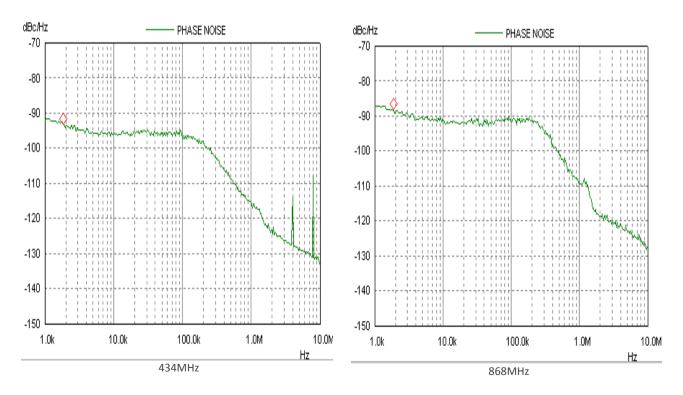


Figure 22: 434MHz and 868MHz phase noise plots



# 13. Manufacturability of Melexis Products with Different Soldering Processes

Our products are classified and qualified regarding soldering technology, solderability and moisture sensitivity level according to following test methods:

#### **Reflow Soldering SMD's (Surface Mount Devices)**

- IPC/JEDEC J-STD-020
   Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices (classification reflow profiles according to table 5-2)
- EIA/JEDEC JESD22-A113
   Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing (reflow profiles according to table 2)

#### Wave Soldering SMD's (Surface Mount Devices) and THD's (Through Hole Devices)

- EN60749-20
  - Resistance of plastic- encapsulated SMD's to combined effect of moisture and soldering heat
- EIA/JEDEC JESD22-B106 and EN60749-15
   Resistance to soldering temperature for through-hole mounted devices

#### Iron Soldering THD's (Through Hole Devices)

EN60749-15
 Resistance to soldering temperature for through-hole mounted devices

#### Solderability SMD's (Surface Mount Devices) and THD's (Through Hole Devices)

 EIA/JEDEC JESD22-B102 and EN60749-21 Solderability

For all soldering technologies deviating from above mentioned standard conditions (regarding peak temperature, temperature gradient, temperature profile etc) additional classification and qualification tests have to be agreed upon with Melexis.

The application of Wave Soldering for SMD's is allowed only after consulting Melexis regarding assurance of adhesive strength between device and board.

Melexis is contributing to global environmental conservation by promoting **lead free** solutions. For more information on qualifications of **RoHS** compliant products (RoHS = European directive on the Restriction Of the use of certain Hazardous Substances) please visit the quality page on our website: <a href="http://www.melexis.com/quality.aspx">http://www.melexis.com/quality.aspx</a>

#### 14. ESD Precautions

Electronic semiconductor products are sensitive to Electro Static Discharge (ESD). Always observe Electro Static Discharge control procedures whenever handling semiconductor products.



# 15. Package Information

The device MLX73290-M is RoHS compliant.

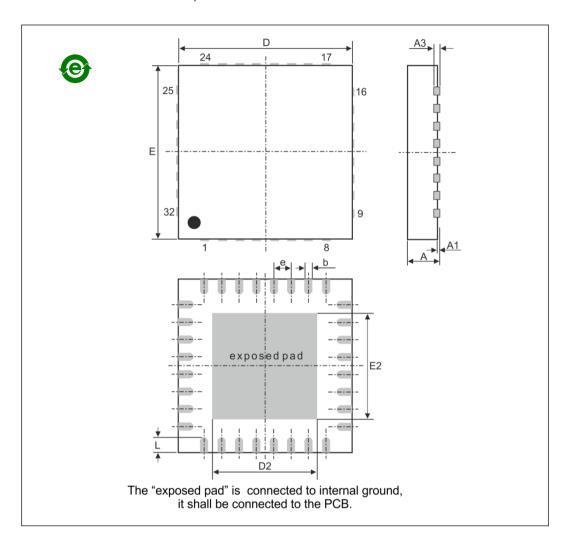


Figure 23: 32L QFN 5x5 Quad

all Dimension in mm										
	D	E	D2	E2	Α	A1	А3	L	е	p
min	4.75	4.75	3.00	3.00	0.80	0	0.20	0.3	0.50	0.18
max	5.25	5.25	3.25	3.25	1.00	0.05		0.5		0.30
all Dimension in inch										
min	0.187	0.187	0.118	0.118	0.0315	0	0.0079	0.0118	0.0197	0.0071
max	0.207	0.207	0.128	0.128	0.0393	0.002		0.0197		0.0118

Table - 32L QFN5x5



## 16. Contact

For the latest version of this document, go to our website at www.melexis.com.

For additional information, please contact our Direct Sales team and get help for your specific needs:

Europe, Africa	Telephone: +32 13 67 04 95			
	Email: sales_europe@melexis.com			
Americas	Telephone: +1 603 223 2362			
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